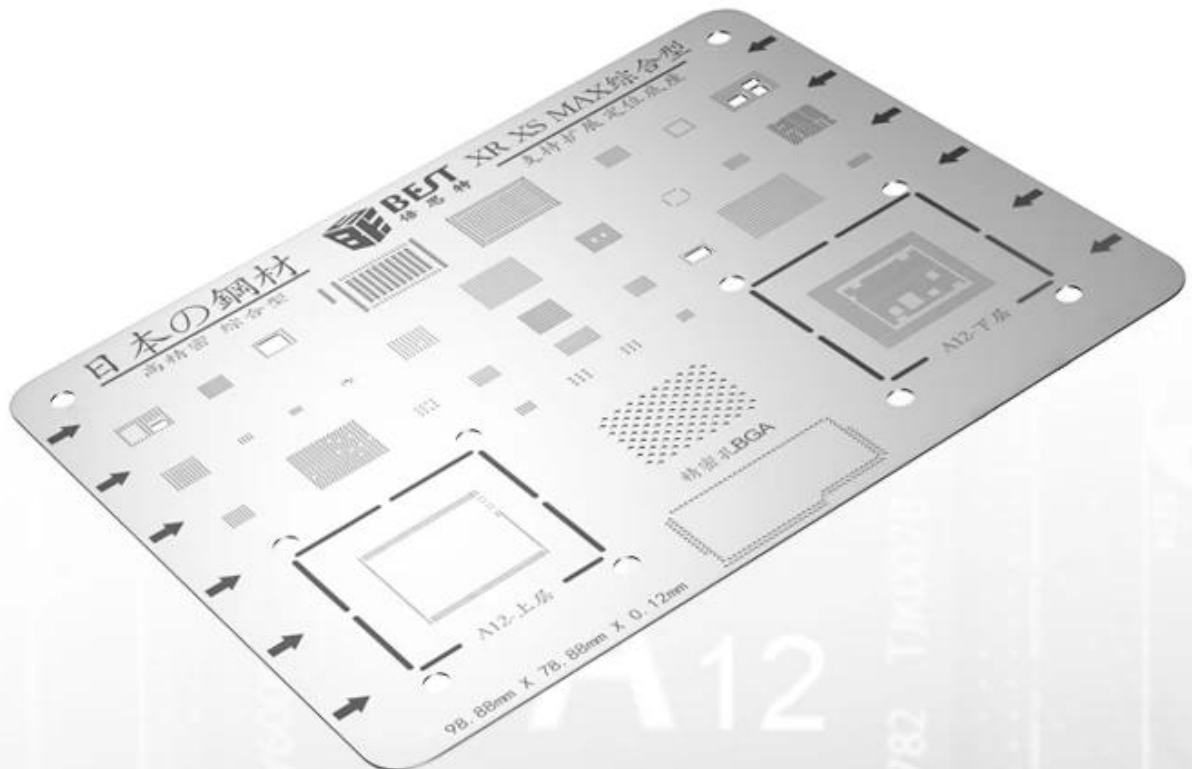


# REBALLING STENCIL

— iPhone CPU series —



SEMI-ETCHING PROCESS



COOLING HOLE DESIGN

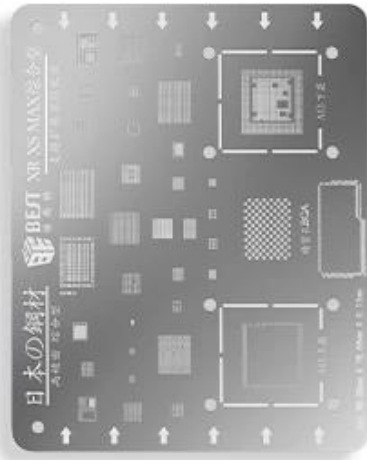


PRECISE ALIGNMENT



SQUARE HOLE

## Product Usage



MATERIAL	Imported steel
BRAND	BESTOOL
PRODUCT NAME	Reballing Stencil
WEIGHT	7g /3.8g
TYPE	Precise alignment Strong toughness Non-stick ti

### ▼ PRODUCT CHARACTERISTICS

This product is used for BGA tinning repair of iPhone series. It adopts imported steel material, anti-rolling anti-deformation, automatic alignment, precise hole position, non-stick tin, good toughness and off-grid.

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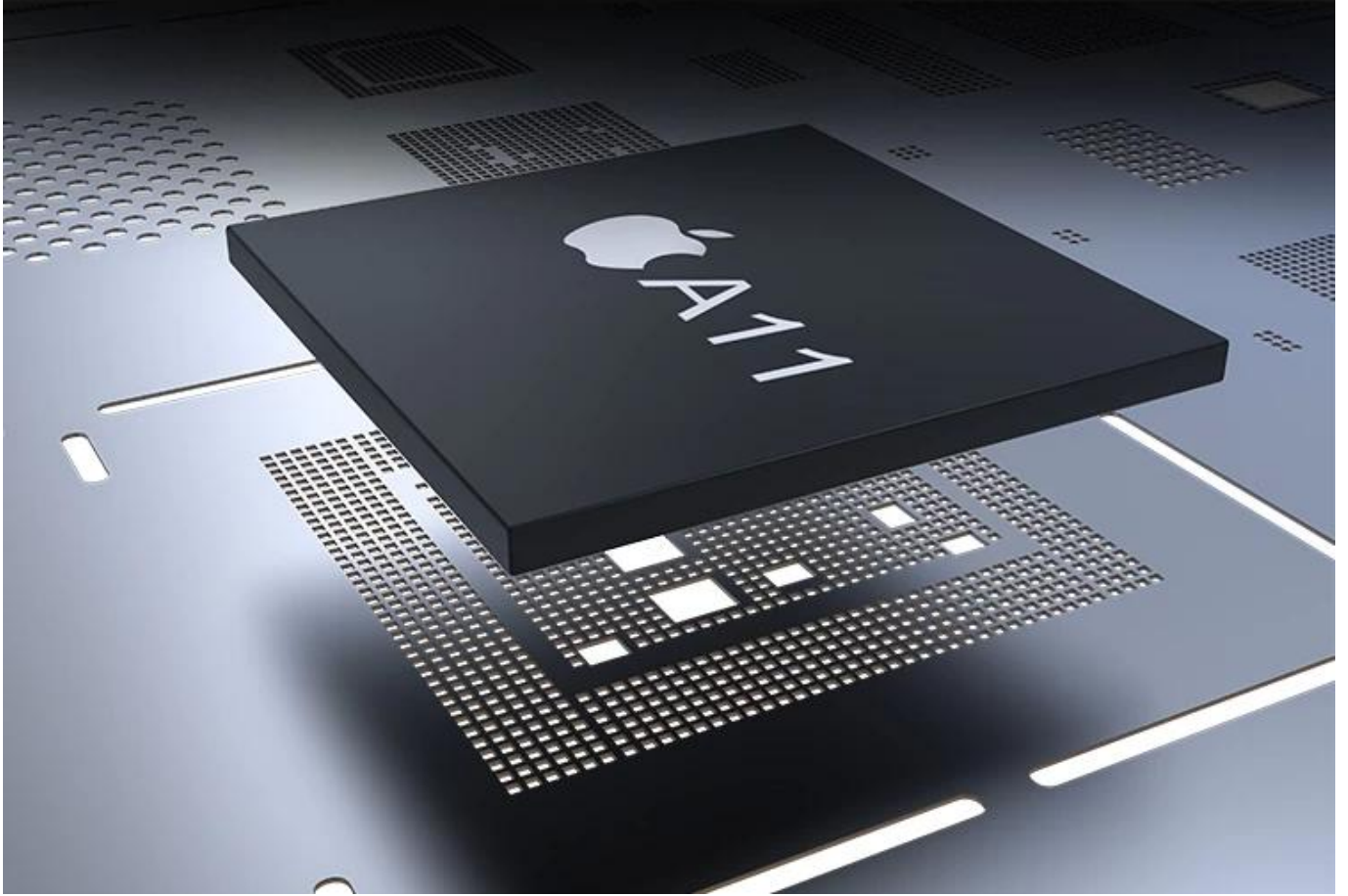


## IMPORTED STEEL

### HIGH TOUGHNESS

GOOD PRODUCTS ARE NOT ONLY  
EXCELLENT FORGING PROCESSES,  
BUT THE REAL CORE LIES IN THE  
SELECTION OF DELICATE MATERIALS.

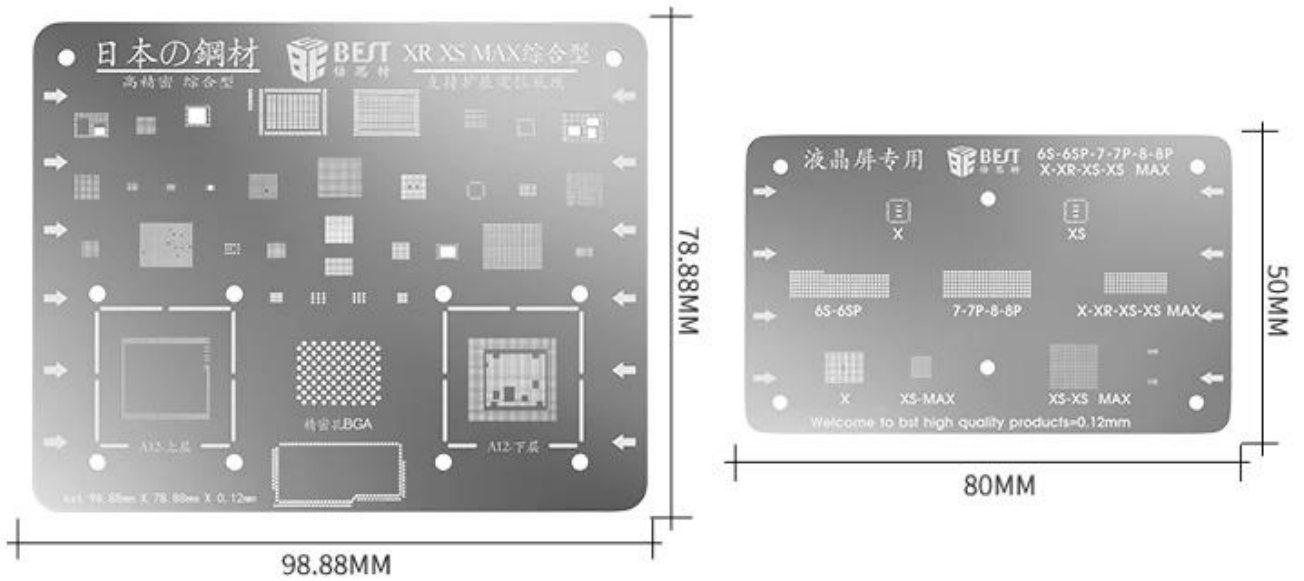
Easily mounted on the steel mesh to make the chip fit more closely with the mesh  
Therefore, the chip after tinning is "more precise"



Imported steel  
Hard and wear resistant  
Accurate to the hole



# PRODUCT SIZE



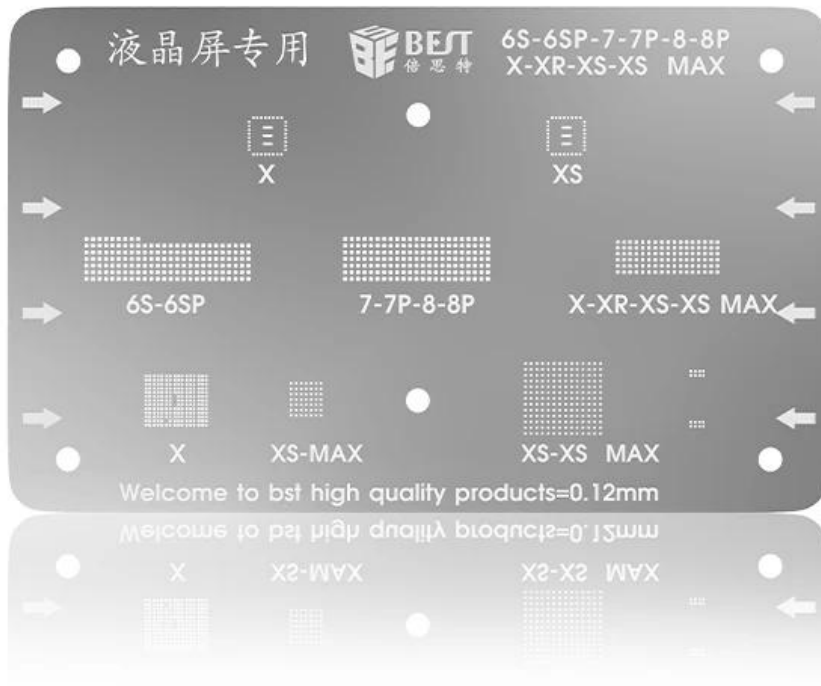
Thin to 0.12mm

Precise die-casting **form heating**

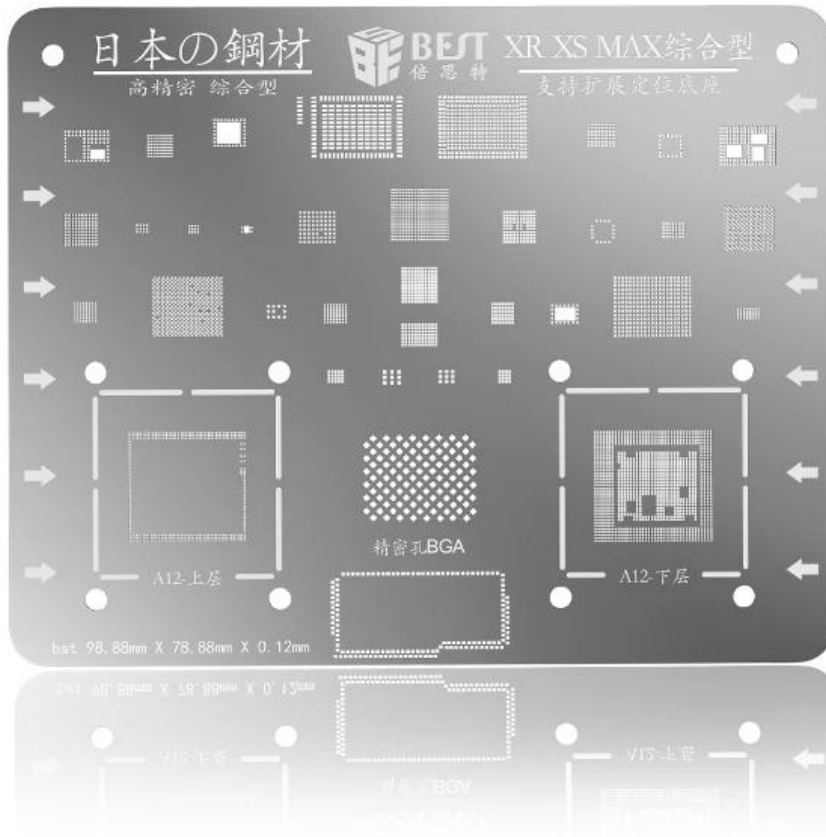


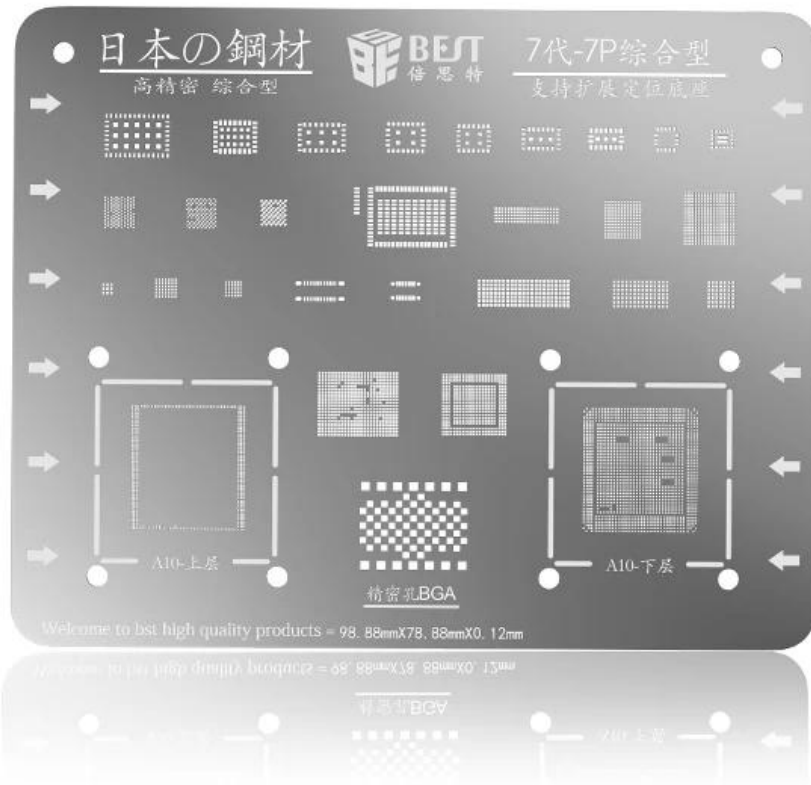
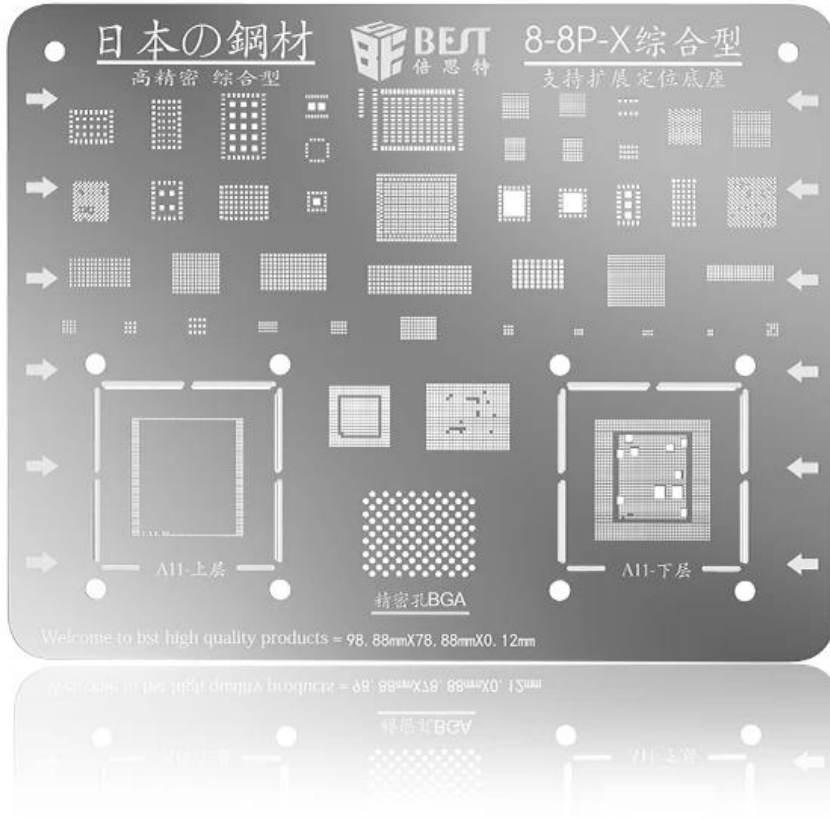


# 6S-6SP-7-7P-8-8P-X-XR-XS-XS MAX

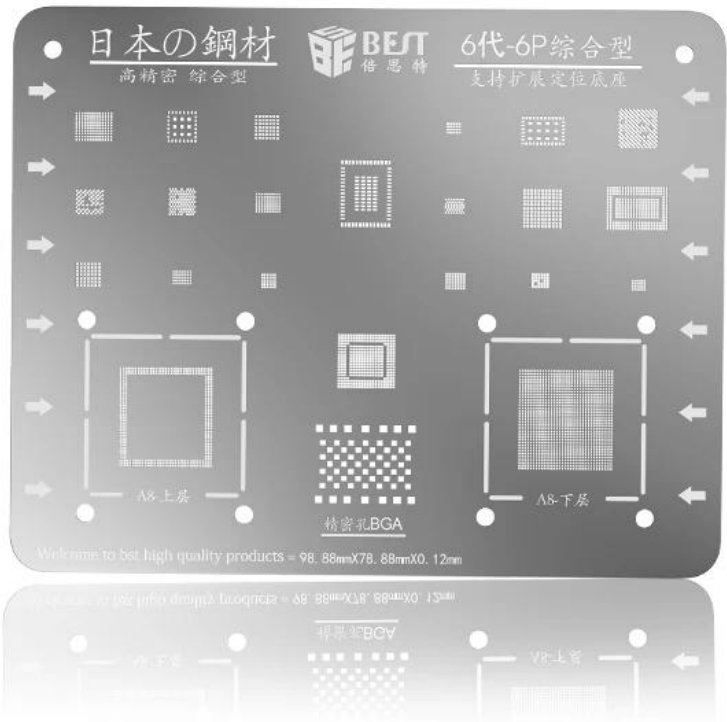
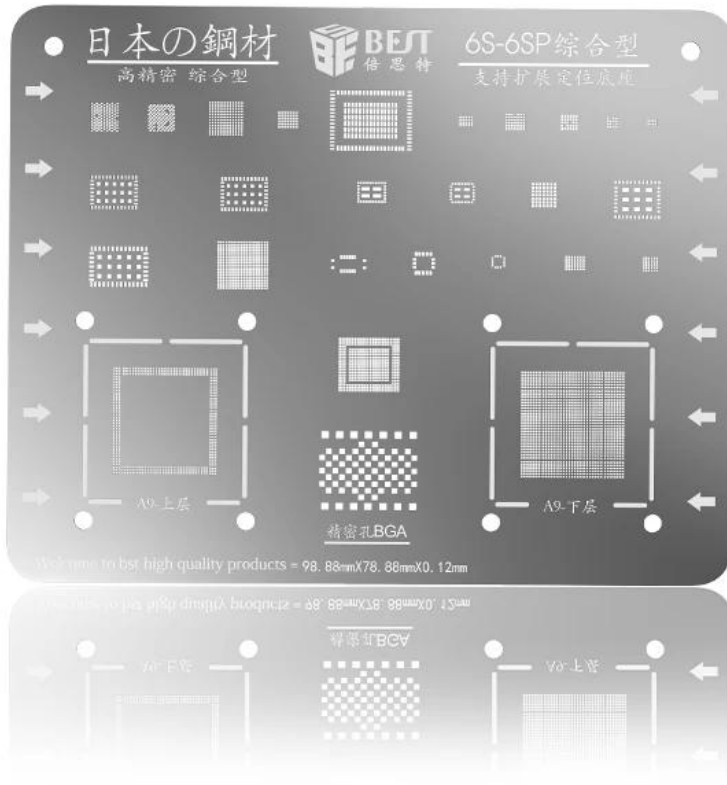



# XR-XS-XS MAX COMPREHENSIVE

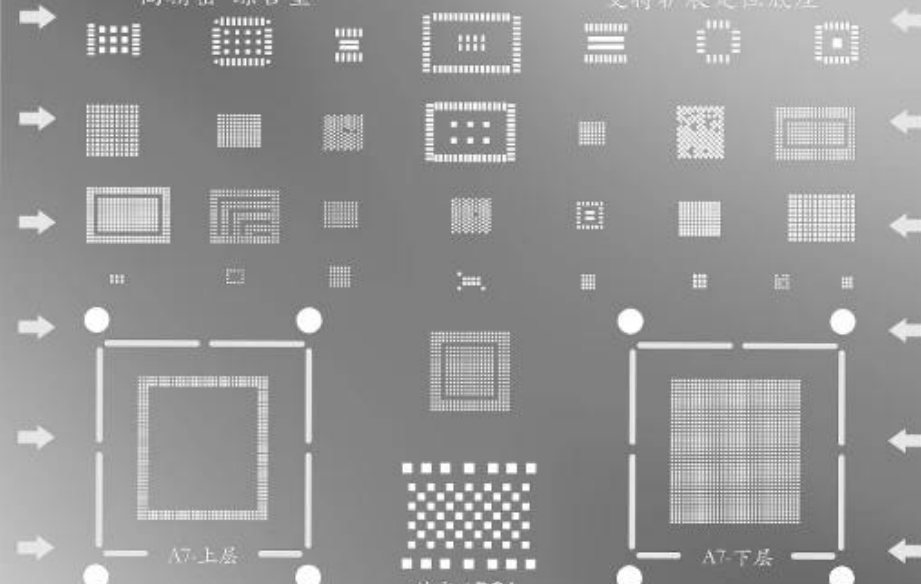


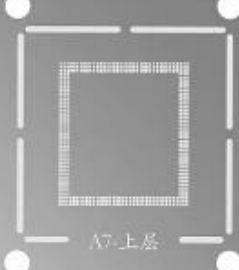






● **日本の鋼材**  **5代-5C/5S综合型** ●  
高精密 综合型 倍思特 支持扩展定位底座



A7-上层  A7-下层

精密孔BGA

Welcome to bst high quality products - 98. 88mmX78. 88mmX0. 12mm

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